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PATENT ABSTRACTS OF JAPAN

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KOYAMA TORU**(54) MANUFACTURE OF WINDING FOR RESIN MOLD ELECTRIC MACHINE****(57)Abstract:**

PURPOSE: To obtain winding which is excellent in a wetproof property and has a high heat resisting property by a method wherein a bonding agent for combining insulating base materials of two kinds or more containing mica is discontinuously treated, an insulating tape is manufactured, and wound, and insulating resin is impregnated.

CONSTITUTION: A bonding agent for combining insulating base materials of two kinds or more of mica, glass, etc. is discontinuously treated, and a mica insulating tape 2 is manufactured which has discontinuous mica binding layers 1. Silicon resin is preferably used as a mica binder, and the discontinuous layers are formed in such a manner that water is added to a mica binder solution to produce a binder under an emulsifying condition, the insulating base materials are pasted by the binder, heated to volatilize a solvent and water, and spotty portions are made up. The mica insulating tape 2 is wound, thermohardening solventless insulating varnish 3 is impregnated under a vacuum condition, and an insulating layer is formed. Thus, a heat resisting property belonging to H class ~ C class and a high wetproof property can be obtained.

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